

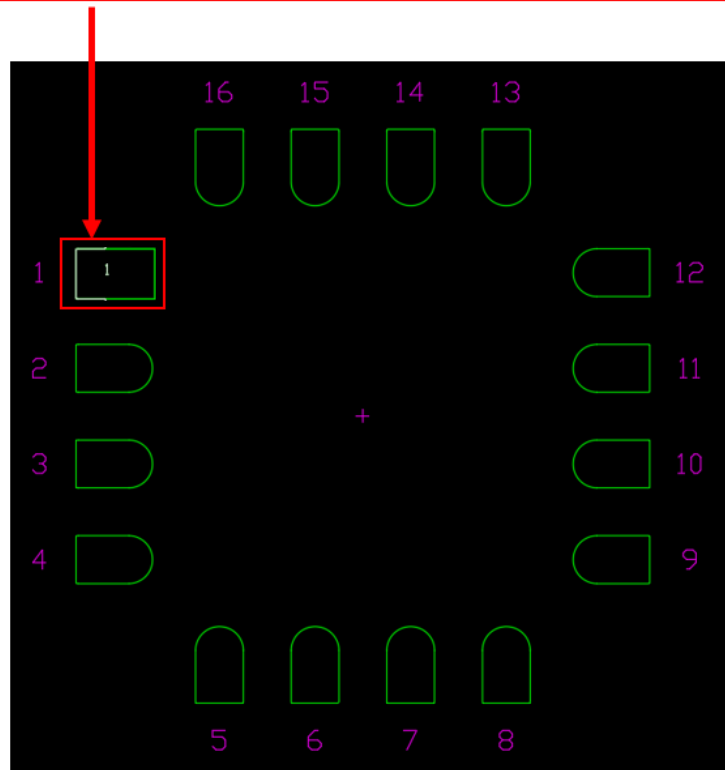
Bill Of Materials (BOM)

MATERIAL	FROM:	TO:	REMARKS
Die Attach Film	Ablestik 8006NS	Ablestik ATB-125	From screen print to DAF
Wire	2N Gold 0.8mil	2N Gold 0.8mil	Same
Mold Compound	Sumitomo G700	Sumitomo G700LA	Same base material
Leadframe	C7025	C7025	Same; Roughened Cu

Pin 1 Identifier

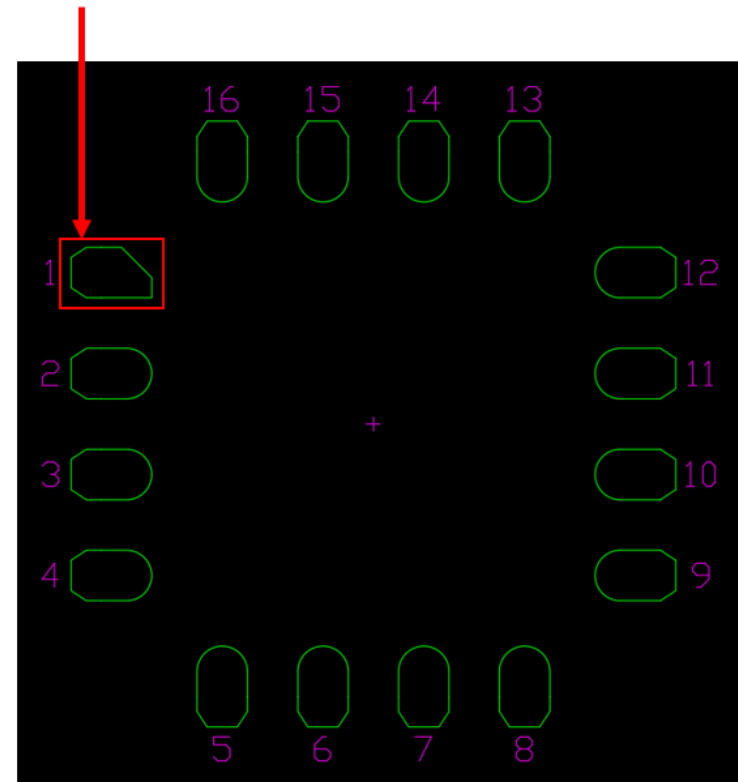
FROM :

Pin 1 Identifier – Rectangular Shape different from other Leads



TO :

Pin 1 Identifier – Chamfer Shape different from other Leads



[illegible]

Assembly Site Transfer of AD5592R LFCSP Product to ASE Chungli

Qualification Plan Summary for AD5592R LFCSP at ASE Chungli

TEST	SPECIFICATION	SAMPLE SIZE	ESTIMATED COMPLETION DATE
Temperature Cycle Test (TCT)*	JESD22-A104	3 x 77	Aug 2018
Solder Heat Resistance Test (SHR)*	J-STD-020	3 x 11	Aug 2018
Unbiased Highly Accelerated Stress Test (uHAST)*	JESD22-A118	3 x 77	Aug 2018
High Temperature Storage (HTS)	JESD22-A103	1 x 77	Aug 2018
Temperature Humidity Bias Test (THB)	JESD22-A101	3 x 77	Aug 2018

* Preconditioned per JEDEC/IPC J-STD0020.